

TIPD177 REV E1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
I PCB1	1		TIPD177	Any	Printed Circuit Board	
C1, C2, C12, C13	4	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C3, C4, C14, C15	4	560pF	GRM1885C1H561JA01D	MuRata	CAP, CERM, 560 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C5	1	2.2uF	GRM316R61E225KA12D	MuRata	CAP, CERM, 2.2uF, 25V, +/-10%, X5R, 1206	1206
C6, C7	2	10uF	C3216X5R1C106M	TDK	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	1206
C8, C9, C10, C11, C16, C17	6	0.1uF	GRM188R71H104KA93D	MuRata	CAP, CERM, 0.1 uF, 50 V, +/- 10%, X7R, 0603	0603
H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
J1	1		39544-3004	Molex	Terminal Block, 4x1, 5.08mm, TH	4x1 Terminal Block
J2	1		5-146261-1	TE Connectivity	Header, 100mil, 2x1, Gold, TH	Header, 2x1, 100mil
J3, J8	2		PBC03SAAN	Sullins Connector Solutions	Header, 100mil, 3x1, Gold, TH	PBC03SAAN
J4, J7	2		112404	Amphenol Connex	Connector, TH, BNC	Amphenol_112404
J5	1		ED555/3DS	On-Shore Technology	Terminal Block, 3.5mm Pitch, 3x1, TH	10.5x8.2x6.5mm
J6	1		SJ-3523-SMT	CUI Inc.	Audio Jack, 3.5mm, Stereo, R/A, SMT	Audio Jack SMD
LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W
R1, R2, R13, R14	4	2.32k	RT0603BRD072K32L	Yageo America	RES, 2.32 k, 0.1%, 0.1 W, 0603	0603
R3, R4, R15, R16	4	1.58k	RT0603BRD071K58L	Yageo America	RES, 1.58 k, 0.1%, 0.1 W, 0603	0603
R5, R6, R17, R18	4	560	RG1608P-561-B-T5	Susumu Co Ltd	RES, 560, 0.1%, 0.1 W, 0603	0603
R7	1	24.9k	RT0603BRD0724K9L	Yageo America	RES, 24.9 k, 0.1%, 0.1 W, 0603	0603
R8	1	14.7k	RT0603BRD0714K7L	Yageo America	RES, 14.7 k, 0.1%, 0.1 W, 0603	0603
R9, R10, R11, R12, R19, R20, R21, R22	8	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
R23	1	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0k ohm, 1%, 0.1W, 0603	0603
U1, U3	2		OPA1612AIDRGR	Texas Instruments	SoundPlus High-Performance, Bipolar-Input Audio Operational Amplifiers, DRG0008A	DRG0008A
U2	1		OPA1622IDRCR	Texas Instruments	SoundPlus High-Fidelity, Bipolar-Input, Audio Operational Amplifier, DRC0010J	DRC0010J
FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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